

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3220	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/27 15:47
S1	0	("10798540").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:43
S2	228	(conductive adj contact adj pad) and (dielectric) and (regions)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 18:09
S3	11	(conductive adj contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 18:13
S4	260	(contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:45
S5	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:54
S6	0	S5 and ((solder near paste) with (opening and via and trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:56
S7	47	S5 and ((solder near paste) with (opening via trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:28

S8	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:29
S9	28	S8 and ((solder near paste) and (second adj substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:30
S10	65	(contact adj pad) and (dielectric) and (solder near paste) and (second adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:34
S11	49	S10 and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:35
S12	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:47
S13	5194150	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) or (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:48
S14	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50
S15	131	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50

S16	2	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated adj circuit adj package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:51
S17	28312	flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:44
S19	825	S17 and (contact adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:47
S20	18	S19 and (solder adj paste) with (opening via trench hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:46
S21	548	S19 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:48
S22	82	S21 and (solder near2 (wet wettable))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:49
S23	2	("6322903").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:41
S27	776	S17 and (bond adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:48